

BAS385

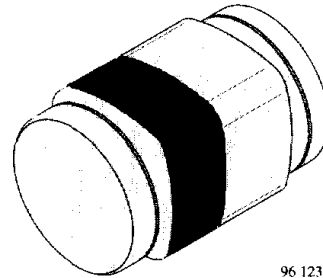
Vishay Telefunken



Schottky Barrier Diode

Features

- Integrated protection ring against static discharge
- Very low forward voltage



96 12315

Applications

Applications where a very low forward voltage is required

Absolute Maximum Ratings

$T_j = 25^\circ\text{C}$

Parameter	Test Conditions	Type	Symbol	Value	Unit
Reverse voltage			V_R	30	V
Peak forward surge current	$t_p = 10 \text{ ms}$		I_{FSM}	5	A
Repetitive peak forward current	$t_p \leq 1 \text{ s}$		I_{FRM}	300	mA
Forward current			I_F	200	mA
Average forward current	$V_{RWM}=25\text{V}$		I_{FAV}	200	mA
Junction temperature			T_j	125	$^\circ\text{C}$
Storage temperature range			T_{stg}	-65...+150	$^\circ\text{C}$

Maximum Thermal Resistance

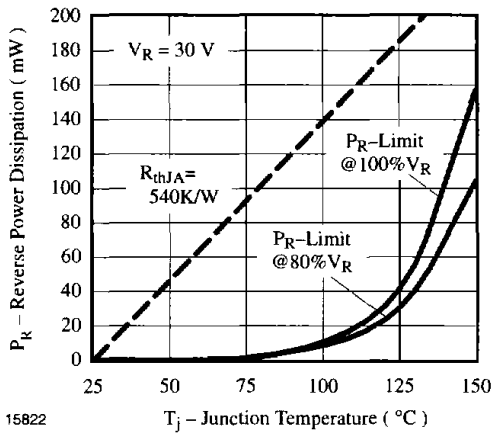
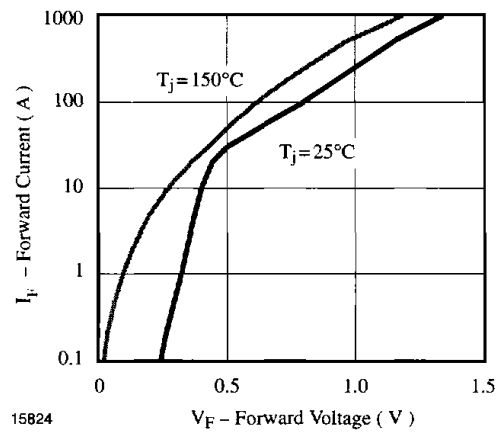
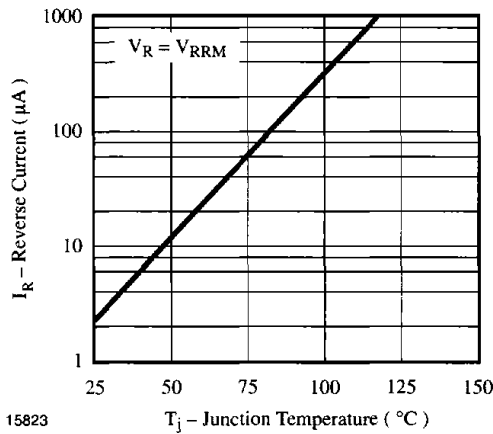
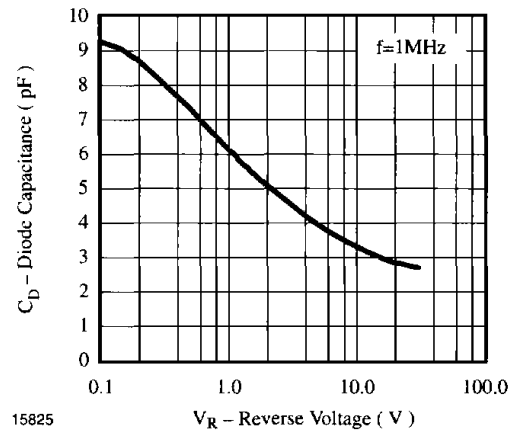
$T_j = 25^\circ\text{C}$

Parameter	Test Conditions	Symbol	Value	Unit
Junction ambient	on PC board 50mmx50mmx1.6mm	R_{thJA}	320	K/W

Electrical Characteristics

$T_j = 25^\circ\text{C}$

Parameter	Test Conditions	Type	Symbol	Min	Typ	Max	Unit
Forward voltage	$I_F=0.1\text{mA}$		V_F			240	mV
	$I_F=1\text{mA}$		V_F			320	mV
	$I_F=10\text{mA}$		V_F			400	mV
	$I_F=30\text{mA}$		V_F			500	mV
	$I_F=100\text{mA}$		V_F			800	mV
Reverse current	$V_R=25\text{V}$, $t_p=300\mu\text{s}$		I_R			2.3	μA
Diode capacitance	$V_R=1\text{V}$, $f=1\text{MHz}$		C_D			10	pF

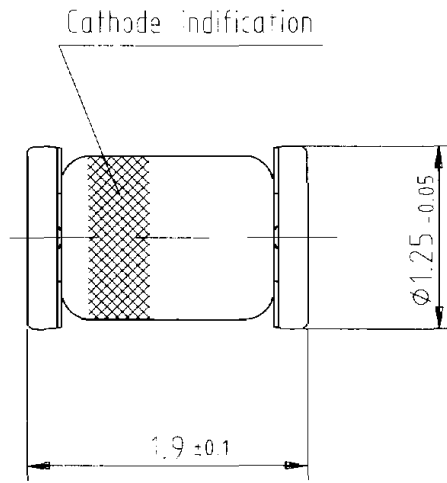
Characteristics ($T_j = 25^\circ\text{C}$ unless otherwise specified)

Figure 1. Max. Reverse Power Dissipation vs. Junction Temperature

Figure 3. Forward Current vs. Forward Voltage

Figure 2. Reverse Current vs. Junction Temperature

Figure 4. Diode Capacitance vs. Reverse Voltage

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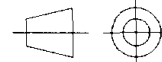
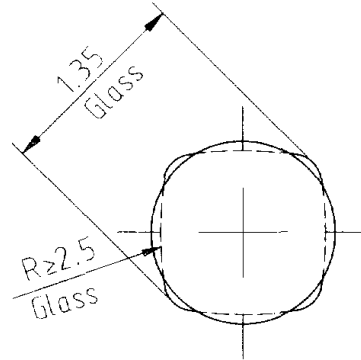
Vishay Telefunken



Dimensions in mm



Glass case
Micro MELF



technical drawings
according to DIN
specifications

96 12072